描述 / Descriptions

TO-252 塑封封装 N 沟道场效应管。

N-CHANNEL MOSFET in a TO-252 Plastic Package.

特征 / Features

$R_{DS(on)}$小，门电荷低，C_{rss}小，开关速度快，符合 AEC-Q101 标准高可靠性要求，无卤产品。

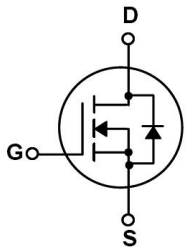
Low $R_{DS(on)}$,low gate charge, low C_{rss}, fast switching, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

用途 / Applications

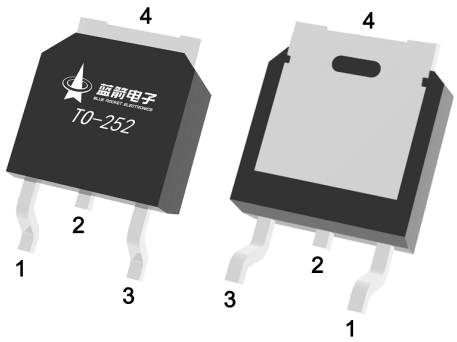
用于低压电路如：汽车电路、DC/DC 转换、便携式产品的电源高效转换，满足汽车应用的严格要求。

Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products, Meet the stringent requirements of automotive applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1：G　　PIN 2：D　　PIN 3：S　　PIN 4：D

印章代码 / Marking

见印章说明。

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

参数 Parameter		符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage		V_{DSS}	40	V
Drain Current		I_D(Tc=25℃)	164	A
Drain Current - Pulsed		I_{DM}	328	A
Gate-Source Voltage		V_{GS}	±20	V
Avalanche Current		I_{AS}	33.2	A
Single Pulsed Avalanche Energy(L=0.5mH)		E_{AS}	880	mJ
Power Dissipation		P_D(Tc=25℃)	125	W
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	℃
Thermal Resistance-Junction to Ambient	t≤10s	$R_{\theta JA}$	17	℃/W
	Steady-State		47	
Thermal Resistance-Junction to Case	Steady-State	$R_{\theta JC}$	1	

电性能参数 / Electrical Characteristics(Ta=25℃)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	40			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=40V V_{GS}=0V			1.0	μA
Gate-Body Leakage Current Forward	I_{GSS}	V_{GS}=±20V V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} I_D=250μA	1.0	1.8	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V I_D=20A		2.5	2.8	mΩ
		V_{GS}=4.5V I_D=10A		3.1	3.5	
Drain-Source Diode Forward Voltage	V_{SD}	V_{GS}=0V I_S=1A			1.2	V
Gate resistance	R_g	V_{GS}=0V V_{DS}=0V, f=1MHz		2		Ω
Input Capacitance	C_{iss}	V_{DS}=25V V_{GS}=0V f=1.0MHz		10850		pF
Output Capacitance	C_{oss}			830		
Reverse Transfer Capacitance	C_{rss}			750		
Total Gate Charge	$Q_{g(10V)}$	V_{GS}=10V, V_{DS}=20V, I_D=20A		50		nC
Total Gate Charge	$Q_{g(4.5V)}$			23		
Gate Source Charge	Q_{gs}			9		
Gate Drain Charge	Q_{gd}			6		

电性能参数 / Electrical Characteristics(Ta=25℃)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=20V R_L=1Ω R_{GEN}=3Ω		11		ns
Turn-On Rise Time	t_r			11		
Turn-Off Delay Time	$t_{d(off)}$			40		
Turn-Off Fall Time	t_f			10		

电参数曲线图 / Electrical Characteristic Curve

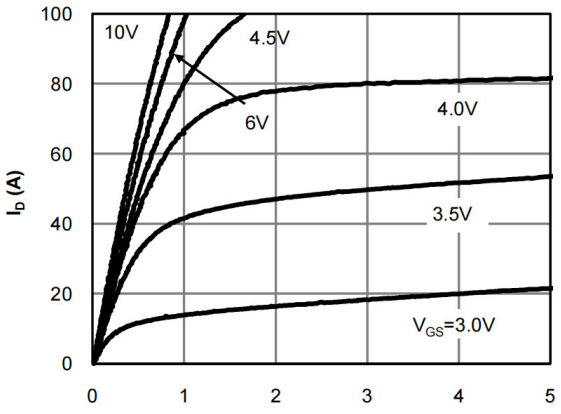


Fig 1: On-Region Characteristics

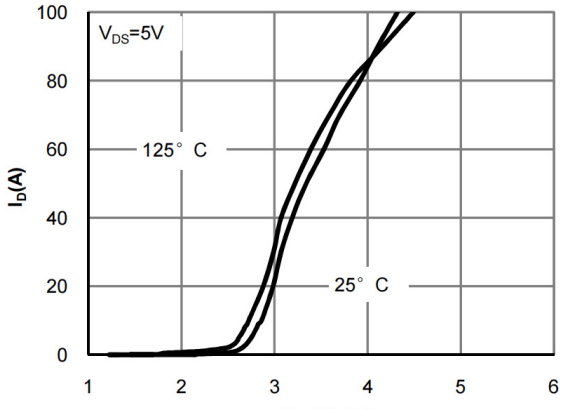


Figure 2: Transfer Characteristics

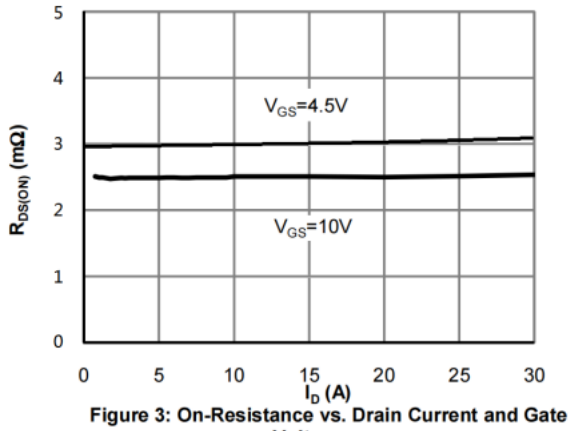


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

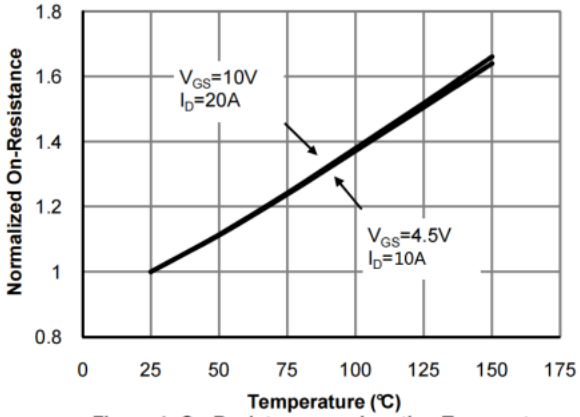


Figure 4: On-Resistance vs. Junction Temperature

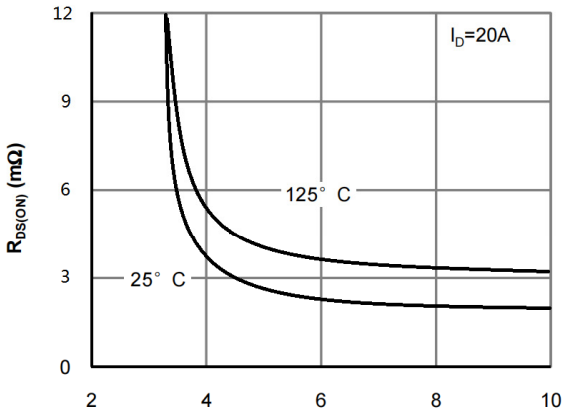


Figure 5: On-Resistance vs. Gate-Source Voltage

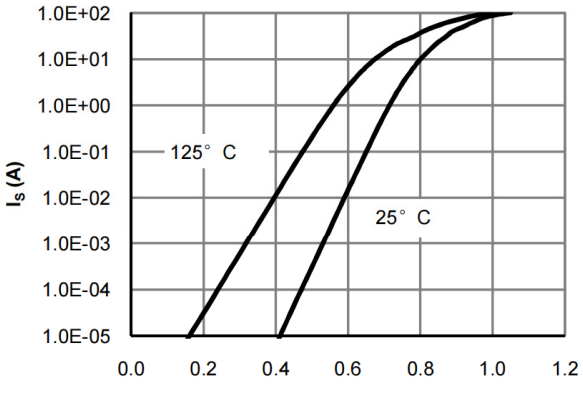


Figure 6: Body-Diode Characteristics

电参数曲线图 / Electrical Characteristic Curve

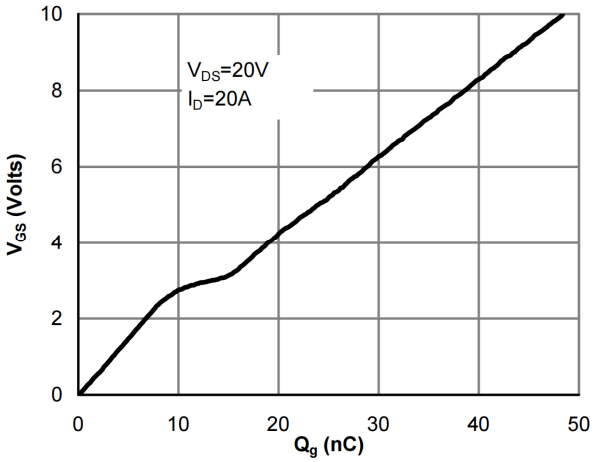


Figure 7: Gate-Charge Characteristics

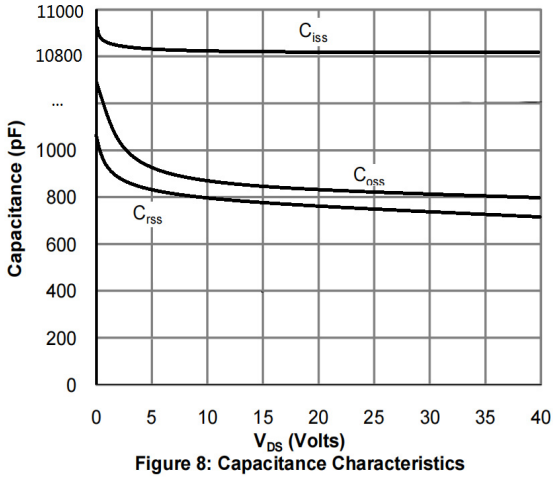


Figure 8: Capacitance Characteristics

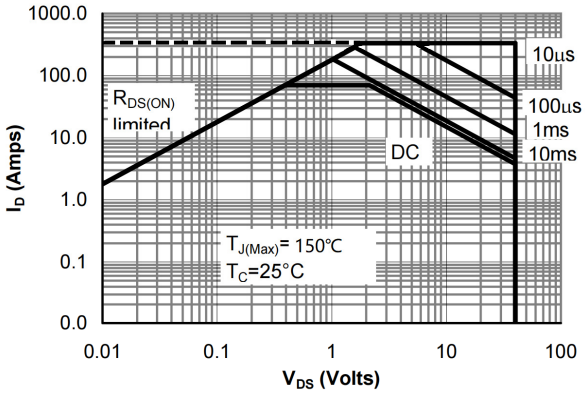


Figure 9: Maximum Forward Biased Safe Operating Area

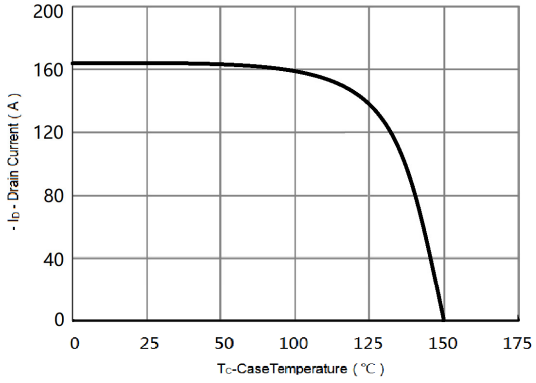


Figure10. Maximum Continuous Drain Current Vs Case Temperature

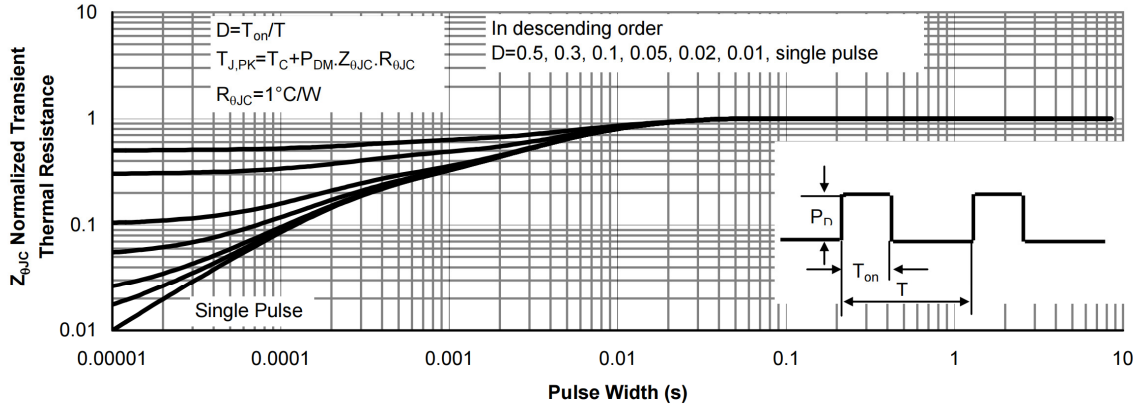
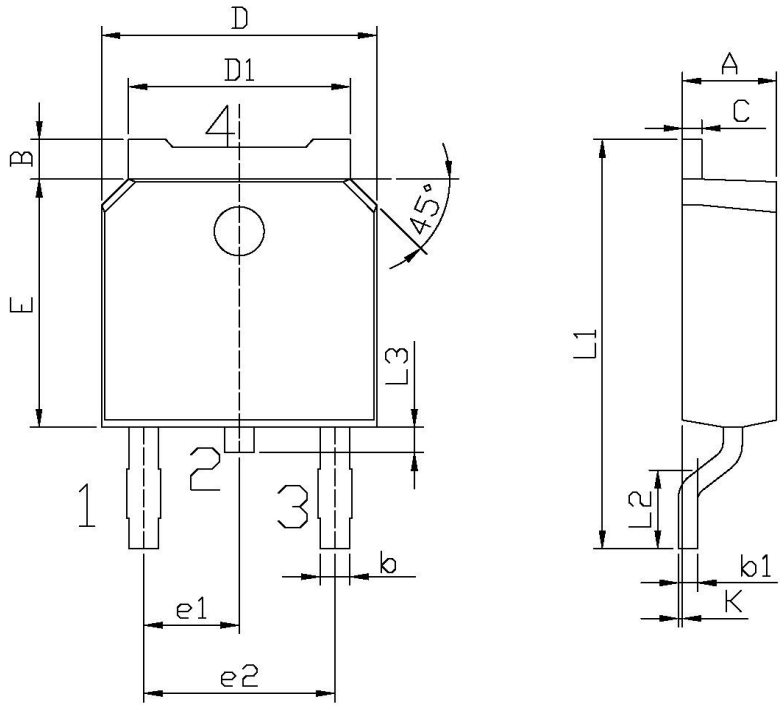


Figure 11: Normalized Maximum Transient Thermal Impedance

外形尺寸图 / Package Dimensions

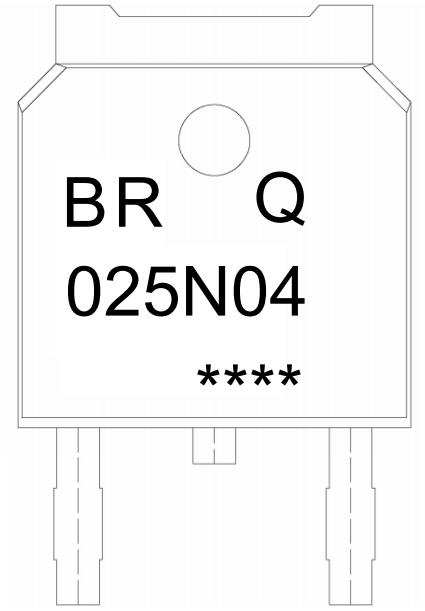


单位：mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.70	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.85	10.35
C	0.45	0.55	L2	1.70	2.00
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

印章说明 / Marking Instructions



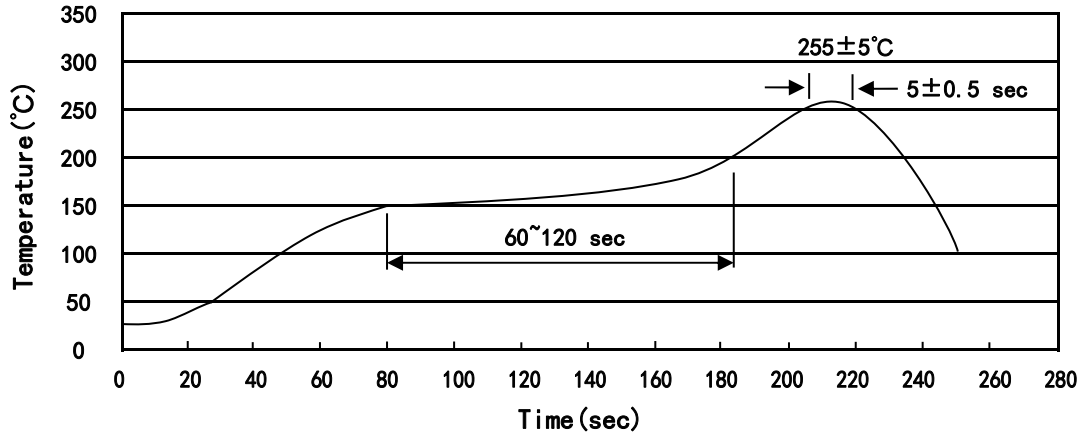
说明：

BR：	为公司代码
Q：	为汽车无卤产品标识
025N04：	为型号代码
****：	为生产批号代码，随生产批号变化

Note:

BR:	Company Code
Q:	Automobile halogen-free product Code
025N04:	Product Type Code
****:	Lot No. Code, code change with Lot No

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：	Note:
1、预热温度 150～200℃，时间 60～120sec;	1.Preheating:150~200℃, Time:60~120sec.
2、峰值温度 255±5℃，时间持续为 5±0.5sec;	2.Peak Temp.:255±5℃, Duration:5±0.5sec.
3、焊接制程冷却速度为 2～10℃/sec.	3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃	时间：10±1 sec.	Temp.:260±5℃	Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit：mm³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	6	30,000	13″ ×16	360×360×50	380×335×366

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit：mm³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

使用说明 / Notices